

Type number	Package	Package description	Total product weight
74AUP1G240GS	SOT1202	X2SON6	0.96210 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935292857132	8	1	260	30 s	1	240	20 s	3	Nijmegen, Netherlands; Seremban, Malaysia; Bangkok, Thailand	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.03146	100.00000	3.26941
		subTotal		0.03146	100.00000	3.26941
Component	Additive	Non hazardous	Proprietary	0.00025	5.00000	0.02598
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00025	5.00000	0.02598
		Silica -amorphous-	7631-86-9	0.00250	50.00000	0.25985
		Epoxy resin system	Proprietary	0.00150	30.00000	0.15591
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.00050	10.00000	0.05197
		subTotal		0.00500	100.00000	0.51969
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.39789	94.51000	41.35611
		Magnesium (Mg)	7439-95-4	0.00063	0.15000	0.06564
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01242	2.95000	1.29087
		Silicon (Si)	7440-21-3	0.00269	0.64000	0.28005
	Pure metal layer	Gold (Au)	7440-57-5	0.00008	0.02000	0.00875
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00690	1.64000	0.71764
		Palladium (Pd)	7440-05-3	0.00038	0.09000	0.03938
subTotal		0.42100	100.00000	43.75844		
Mould Compound	Additive	Misc. Phosphor compounds (generic)	7723-14-0	0.00049	0.10000	0.05103
		Non hazardous	Proprietary	0.01768	3.60000	1.83723
	Filler	Silica fused	60676-86-0	0.43208	88.00000	44.91009
	Polymer	Carbon black	1333-86-4	0.00098	0.20000	0.10207
		Phenolic resin	Proprietary	0.02013	4.10000	2.09240
	Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.01964	4.00000	2.04137	
subTotal		0.49100	100.00000	51.03419		
Wire	Gold alloy	Gold (Au)	7440-57-5	0.01350	99.00000	1.40355
		Palladium (Pd)	7440-05-3	0.00014	1.00000	0.01418
	subTotal		0.01364	100.00000	1.41773	

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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